SN54192, SN54193, SN54LS192, SN54LS193, SN74192, SN74193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECMEBER 1972 - REVISED MARCH 1988

- Cascading Circuitry Provided Internally
- Synchronous Operation
- Individual Preset to Each Flip-Flop
- Fully Independent Clear Input

TYPES TYPICAL MAXIMUM TYPICAL
COUNT FREQUENCY POWER DISSIPATION
'192,'193 32 MHz 325 mW

'192,'193 32 MHz 'LS192,'LS193 32 MHz

95 mW

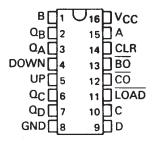
description

These monolithic circuits are synchronous reversible (up/down) counters having a complexity of 55 equivalent gates. The '192 and 'LS192 circuits are BCD counters and the '193 and 'LS193 are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincidently with each other when so instructed by the steering logic. This mode of operation eliminates the output counting spikes which are normally associated with asynchronous (ripple-clock) counters.

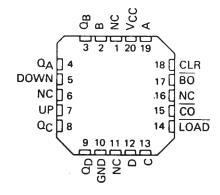
The outputs of the four master-slave flip-flops are triggered by a low-to-high-level transition of either count (clock) input. The direction of counting is determined by which count input is pulsed while the other count input is high.

All four counters are fully programmable; that is, each output may be preset to either level by entering the desired data at the data inputs while the load input is low. The output will change to agree with the data inputs independently of the count pulses. This feature

SN54192, SN54193, SN54LS192, SN54LS193...J OR W PACKAGE SN74192, SN74193...N PACKAGE SN74LS192, SN74LS193...D OR N PACKAGE (TOP VIEW)



SN54LS192, SN54LS193 . . . FK PACKAGE (TOP VIEW)



NC - No internal connection

allows the counters to be used as modulo-N dividers by simply modifying the count length with the preset inputs.

A clear input has been provided which forces all outputs to the low level when a high level is applied. The clear function is independent of the count and load inputs. The clear, count, and load inputs are buffered to lower the drive requirements. This reduces the number of clock drivers, etc., required for long words.

These counters were designed to be cascaded without the need for external circuitry. Both borrow and carry outputs are available to cascade both the up- and down-counting functions. The borrow output produces a pulse equal in width to the count-down input when the counter underflows. Similarly, the carry output produces a pulse equal in width to the count-up input when an overflow condition exists. The counters can then be easily cascaded by feeding the borrow and carry outputs to the count-down and count-up inputs respectively of the succeeding counter.

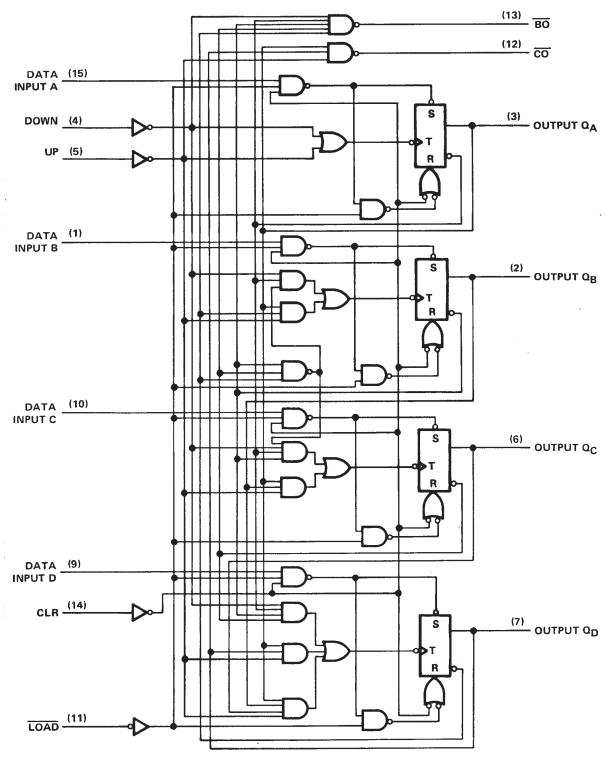
absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

	SN54'	SN54LS'	SN74'	SN74LS'	UNIT
Supply voltage, V _{CC} (see Note 1)	7	7	7	7	V
Input voltage	5.5	7	5.5	7	V
Operating free-air temperature range	- 55	- 55 to 125		0 to 70	
Storage temperature range	-65 to 150		- 65	°C	

NOTE 1: Voltage values are with respect to network ground terminal.



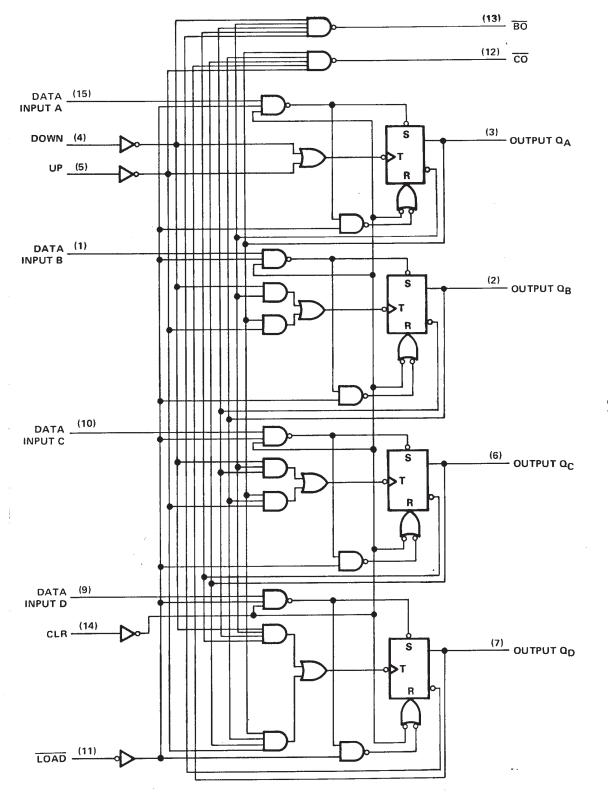
logic diagram (positive logic)



Pin numbers shown are for D, J, N, and W packages.



logic diagram (positive logic)



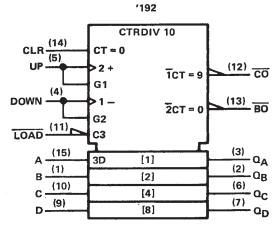
Pin numbers shown are for D, J, N, and W packages.

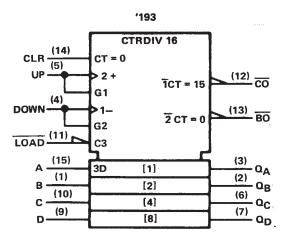


SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

SDLS074 - DECMEBER 1972 - REVISED MARCH 1988

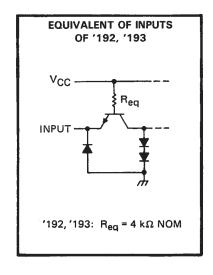
logic symbols†

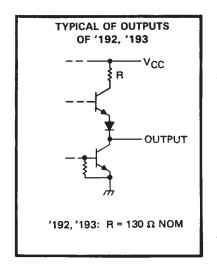


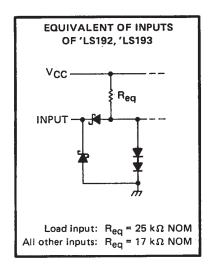


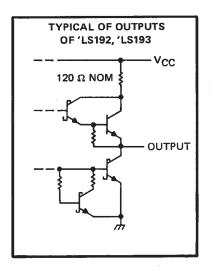
[†]These symbols are in accordance with ANSI/IEEE Std. 91-1984 and IEC Publication 617-12. Pin numbers shown are for D, J, N, and W packages.

schematics of inputs and outputs









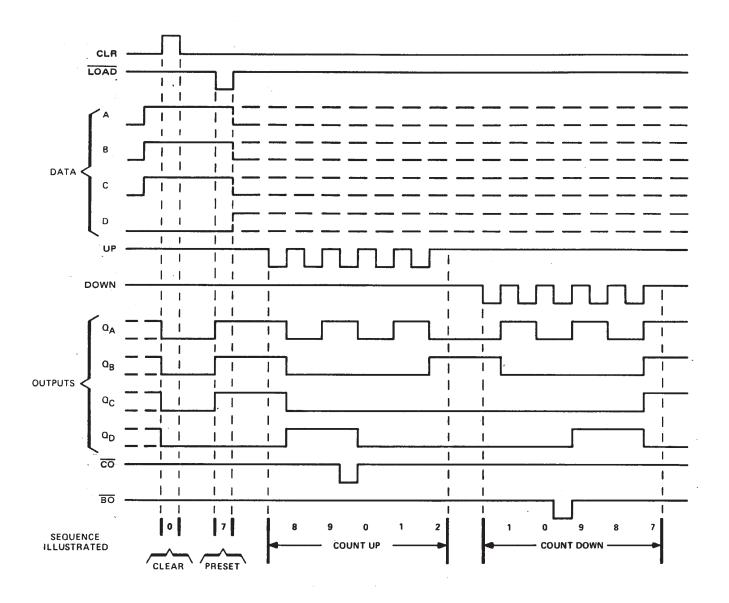


'192, 'LS192 DECADE COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to BCD seven.
- 3. Count up to eight, nine, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, nine, eight, and seven.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.

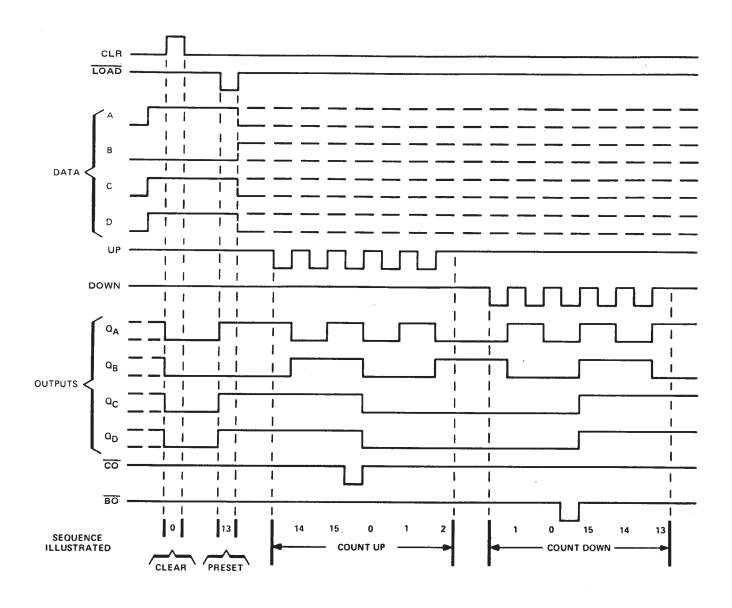


'193, 'LS193 BINARY COUNTERS

typical clear, load, and count sequences

Illustrated below is the following sequence:

- 1. Clear outputs to zero.
- 2. Load (preset) to binary thirteen.
- 3. Count up to fourteen, fifteen, carry, zero, one, and two.
- 4. Count down to one, zero, borrow, fifteen, fourteen, and thirteen.



NOTES: A. Clear overrides load, data, and count inputs.

B. When counting up, count-down input must be high; when counting down, count-up input must be high.



recommended operating conditions

			SN54192 SN54193			SN74192 SN74193			UNIT		
			MIN	NOM	MAX	MIN	NOM	MAX	1		
Vcc	Supply voltage		4.5	5	5.5	4.75	5	5.25	٧		
ГОН	High-level output current			-0.4			-0.4	mA			
loL	Low-level output current	1		16			16	mA			
fclock	Clock frequency		0		25	0		25	MHz		
t _W	Width of any input pulse		20			20			ns		
t _{su}	Data setup time, (see Figure 1)		20			20			ns		
*************	I a lalation a	Data, high or low	0	-		0					
th	th Hold time	LOAD	3			3			ns		
TA	perating free-air temperature		-55		125	0		70	°C		

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST CONDITIONS [†]	SN54192 SN54193			SN74192 SN74193			UNIT
			MIN	TYP‡	MAX	MIN	TYP‡	MAX	
VIH	High-level input voltage		2			2			V
VIL	Low-level input voltage				0.8			8.0	V
VIK	Input clamp voltage	V _{CC} = MIN, I _I = -12 mA			-1.5			-1.5	٧
Voн	High-level output voltage	V _{CC} = MIN, V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = -0.4 mA	2.4	3.4		2.4	3.4		V
VOL	Low-level output voltage	V _{CC} = MIN, V _{IH} = 2 V V _{IL} = 0.8 V, I _{OL} = 16 mA		0.2	0.4		0.2	0.4	٧
Ц	Input current at maximum input voltage	V _{CC} = MAX, V _I = 5.5 V			1			1	mA
11H	High-level input current	V _{CC} = MAX, V ₁ = 2.4 V			40			40	μΑ
liL.	Low-level input current	V _{CC} = MAX, V _i = 0.4 V			-1.6			-1.6	mA
los	Short-circuit output current§	V _{CC} = MAX	-20		-65	-18		-65	mA
Icc	Supply current	V _{CC} = MAX, See Note 2		65	89		65	102	mA

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.

switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER¶	FROM INPUT	TO OUTPUT	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	32		MHz
^t PLH	UP	CO			17	26	
^t PHL	UP I				16	24	ns
tPLH .	DOWN	BO	C _L = 15 pF,		16	24	
tPHL .	DOWN	ВО	$R_L = 400 \Omega$,		16	24	ns
^t PLH	LID OD DOWN		See Figures 1 and 2		25	38	ns
^t PHL	UP OR DOWN	Q	See Figures 1 and 2		31	47	
^t PLH	1015				27	40	
[‡] PHL	LOAD	Q			29	40	ns
^t PHL	CLR	Q			22	35	ns

 $[\]P_{\text{fmax}} \equiv \text{maximum clock frequency}$

 $t_{PHL} \equiv$ propagation delay time, high-to-low-level output



 $[\]ddagger$ All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.

[§] Not more than one output should be shorted at a time.

NOTE 2: I_{CC} is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

tpLH = propagation delay time, low-to-high-level output

SN54LS192, SN54LS193, SN74LS192, SN74LS193 SYNCHRONOUS 4-BIT UP/DOWN COUNTERS (DUAL CLOCK WITH CLEAR)

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recommended operating conditions

			SN54LS192 SN54LS193		SN74LS192 SN74LS193			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	. 5	5.5	4.75	5	5.25	V
ЮН	High-level output current			-400			-400	μΑ
loL	Low-level output current			4			8	mA
fclock	Clock frequency	0		25	0		25	MHz
tw	Width of any input pulse	20			20			ns
	Clear inactive-state setup time	15			15			ns
^t su	Load inactive-state setup time	15			15			ns
	Data setup time (see Figure 1)	20			20			ns
th	Data hold time	5			5			ns
TA	Operating free-air temperature range	-55		125	0		70	°c

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TE	TEST CONDITIONS [†]				SN54LS192 SN54LS193			SN74LS192 SN74LS193		
	·.				MIN	TYP [‡]	MAX	MIN	TYP‡	MAX		
v_{IH}	High-level input voltage				2			2			V	
VIL	Low-level input voltage						0.7			0.8	V	
VIK	Input clamp voltage	V _{CC} = MIN,	I _I = -18 mA				-1.5			-1.5	٧	
V _{OH}	High-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V, , I _{OH} = -400 μΑ		2.5	3.4		2.7	3.4		٧	
VOL	Low-level output voltage	V _{CC} = MIN, V _{IL} = V _{IL} max	V _{IH} = 2 V,	I _{OL} = 4 mA		0.25	0.4		0.15 0.35	0.4	٧	
l _l	Input current at maximum input voltage	V _{CC} = MAX,	V ₁ = 7 V				0.1			0.1	;mA	
ΉΗ	High-level input current	V _{CC} = MAX,	V _I = 2.7 V				20			20	μА	
IIL	Low-level input current	V _{CC} = MAX,	V _I = 0.4 V				-0.4			-0.4	mA	
los	Short-circuit output current§	V _{CC} = MAX			-20		-100	-20		-100	mA	
Icc	Supply current	V _{CC} = MAX,	See Note 2			19	¦34		19	-34	mA	

[†]For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type. ‡All typical values are at V_{CC} = 5 V, T_A = 25°C.

NOTE 2: I_{CC} is measured with all outputs open, clear and load inputs grounded, and all other inputs at 4.5 V.

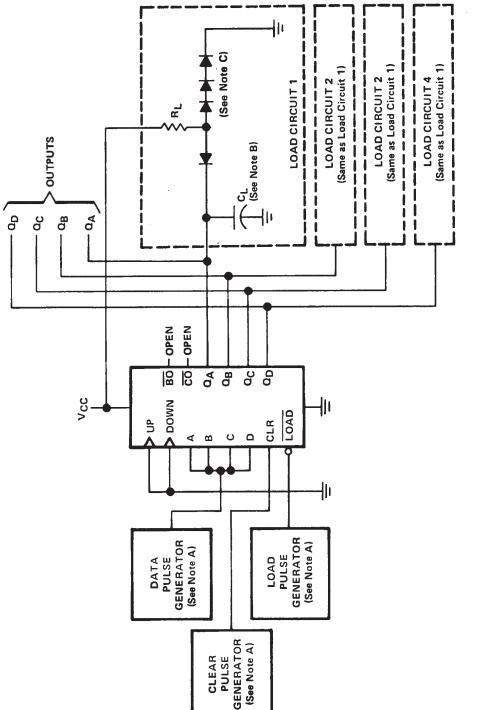
switching characteristics, VCC = 5 V, TA = 25°C

PARAMETER	FROM INPUT	TO OUTPU T	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f _{max}				25	32		MHz
^t PLH	UP	CO			17	26	
t _{PHL}	Or Or	CO			18	24	ns
^t PLH	DOWN	BO	C _L = 15 pF,		16	24	ns
tPHL the transfer of the trans	DOWN	во	$R_L = 2 k\Omega$,		15	24	113
t _{PLH}	UD OD DOWN	0	See Figures 1 and 2		27	38	
t _{PHL}	OF OR DOWN	UP OR DOWN Q	See Figures Fand 2		30	47	ns
^t PLH	1040				24	40	
tPHL	LOAD	Q			25	40	ns
[†] PHL	CLR	a			23	35	ns



[§] Not more than one output should be shorted at a time, and duration of the short-circuit should not exceed one second.

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

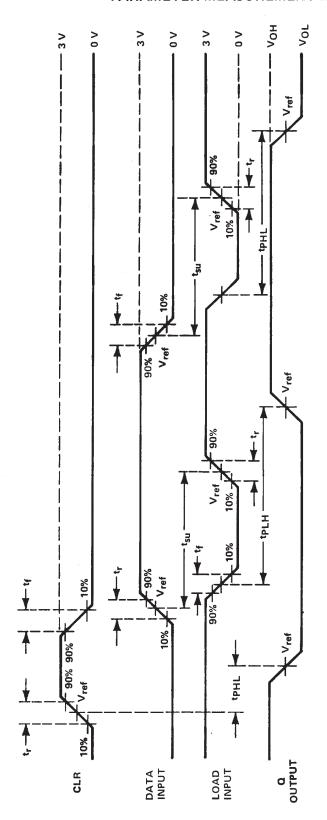
The pulse generators have the following characteristics: Zout ≈ 50 Ω and for the data pulse generator PRR ≤ 500 kHz, duty cycle = 50%; for the load pulse generator PRR is two times data PRR, duty cycle = 50% ë NOTES:

- CL includes probe and jig capacitance.
- Diodes are 1N3064 or equivalent. ன் ப் ப் **ய்**
- t_r and $t_f \leq 7$ ns. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 1A - CLEAR, SETUP AND LOAD TIMES



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: Z_{out} ≈ 50 Ω and for the data pulse generator PRR ≤ 500 kHz, duty cycle = 50%; for the load pulse generator PRR is two times data PRR, duty cycle = 50%

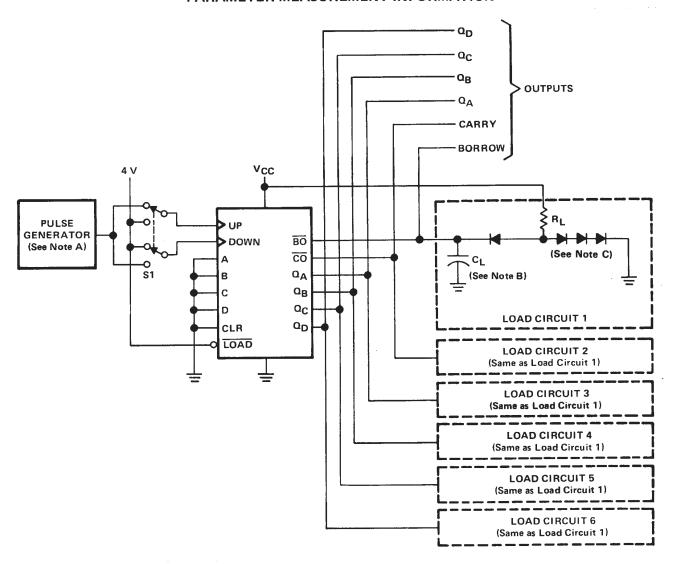
- CL includes probe and jig capacitance.
 - Diodes are 1N3064 or equivalent.
- t_{r} and $t_{f} \leq 7$ ns. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193. といい と

FIGURE 18 - CLEAR, SETUP, AND LOAD TIMES



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PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

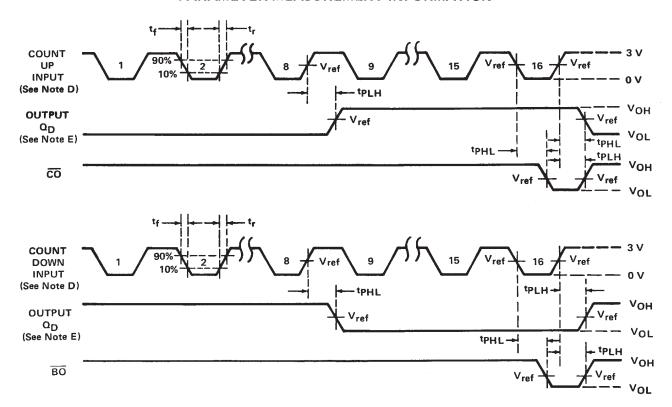
NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, $Z_{out} \approx$ 50 Ω , duty cycle = 50%.

- B. C_L includes probe and jig capacitance.
- C. Diodes are 1N3064 or equivalent.
- D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
- E. Waveforms for outputs $Q_{\mbox{\scriptsize A}}$, $Q_{\mbox{\scriptsize B}}$, and $Q_{\mbox{\scriptsize C}}$ are omitted to simplify the drawing.
- F. t_r and $t_f \le 7$ ns.
- G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2A - PROPAGATION DELAY TIMES



PARAMETER MEASUREMENT INFORMATION



VOLTAGE WAVEFORMS

NOTES: A. The pulse generators have the following characteristics: PRR \approx 1 MHz, Z_{OUt} \approx 50 Ω , duty cycle = 50%.

- B. C_L includes probe and jig capacitance.
- C. Diodes are 1N3064 or equivalent.
- D. Cout-up and dount-down pulse shown are for the '193 and 'LS193 binary counters. Count cycle for '192 and 'LS192 decade counters is 1 through 10.
- E. Waveforms for outputs Q_A , Q_B , and Q_C are omitted to simplify the drawing.
- F. t_r and $t_f \le 7$ ns.
- G. V_{ref} is 1.5 V for '192 and '193, 1.3 V for 'LS192 and 'LS193.

FIGURE 2B - PROPAGATION DELAY TIMES





PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	n MSL Peak Temp ⁽³⁾
5962-9558401QEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
5962-9558401QFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
76006012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7600601EA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
7600601FA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/01309BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
JM38510/01309BEA	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31508B2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/31508BEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/31508BFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/31508SEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/31508SEA	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
JM38510/31508SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
JM38510/31508SFA	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54192J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SN74192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74193N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS192D	OBSOLETE	SOIC	D	16		TBD	Call TI	Call TI
SN74LS192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS192N	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM





6-Dec-2006

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LS193DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN74LS193N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS193N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS193N3	OBSOLETE	PDIP	N	16		TBD	Call TI	Call TI
SN74LS193NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS193NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LS193NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54192J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54192W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54193J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54193W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS193FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS193J	ACTIVE	CDIP	J	16	1	TBD	A42 SNPB	N / A for Pkg Type
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type
SNJ54LS193W	ACTIVE	CFP	W	16	1	TBD	A42	N / A for Pkg Type

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in



PACKAGE OPTION ADDENDUM

6-Dec-2006

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F16)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F16 and JEDEC MO-092AC



FK (S-CQCC-N**)

28 TERMINAL SHOWN

LEADLESS CERAMIC CHIP CARRIER



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
- Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
- E. Reference JEDEC MS-012 variation AC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



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